



Material Content Data Sheet



Sales Product Name	BSS308PE H6327			Issued		4. November 2019		
MA#	MA001627120							
Package	PG-SOT23-3-5			Weight*		9.42 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.004	0.05		468	
	noble metal	gold	7440-57-5	0.017	0.18		1816	
	inorganic material	silicon	7440-21-3	0.261	2.77	3.00	27699	29983
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		64	
	non noble metal	titanium	7440-32-6	0.003	0.03		320	
	non noble metal	chromium	7440-47-3	0.009	0.10		959	
	non noble metal	copper	7440-50-8	3.000	31.85	31.99	318467	319810
wire	non noble metal	copper	7440-50-8	0.076	0.81	0.81	8063	8063
encapsulation	organic material	carbon black	1333-86-4	0.056	0.60		5961	
	plastics	epoxy resin	-	1.207	12.82		128155	
	inorganic material	silicondioxide	60676-86-0	4.352	46.17	59.59	461956	596072
leadfinish	non noble metal	tin	7440-31-5	0.150	1.59	1.59	15883	15883
plating	noble metal	silver	7440-22-4	0.284	3.02	3.02	30189	30189
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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